

## MOS 4096-BIT STATIC RANDOM ACCESS MEMORY

### DESCRIPTION

The Fujitsu MBM2148L is a 1024 word by 4 bit static random access memory with automatic power down. It is fabricated using N-channel silicon gate MOS technology. The memory is fully static and requires no clock or timing strobe. All pins are TTL compatible and a single 5V power supply is required.

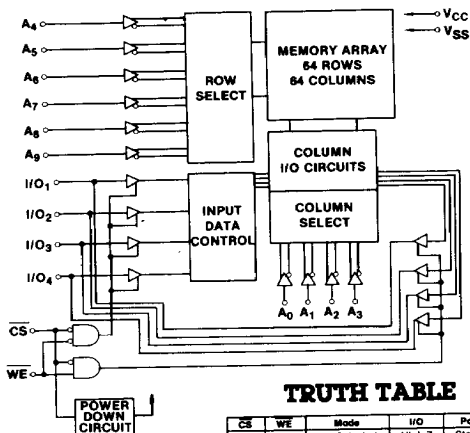
A separate chip select ( $\overline{CS}$ ) pin simplifies multipackage systems

design. It permits the selection of an individual package when outputs are OR-tied, and furthermore on selecting a single package by  $\overline{CS}$  the other deselected packages automatically power down. Fujitsu's MBM2148L offers the advantages of low power dissipation, low cost and high performance.

### FEATURES

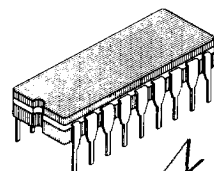
- Organization: 1024 words x 4 bits
- Static operation; no clock or timing strobe required
- Fast access time:  
MBM2148-55L: 55 ns max.  
MBM2148-70L: 70 ns max.
- Low power consumption:  
ICC = 125mA max.  
ISB = 20mA max.
- Single +5V DC supply voltage ( $\pm 10\%$  tolerance)
- Common data input/output
- TTL compatible inputs/outputs
- Three-state output with OR-tie capability
- Chip select for simplified memory expansion, automatic power down
- Standard 18-pin DIP package
- Pin compatible with Intel 2148

### MBM2148 BLOCK DIAGRAM



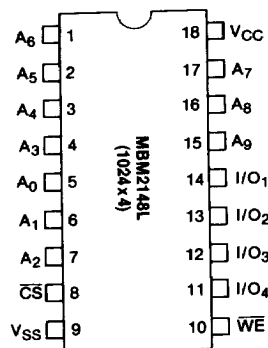
### TRUTH TABLE

CS	WE	Mode	I/O	Power
H	X	Not Selected	High Z	Standby
L	L	Write	DIN	Active
L	H	Read	DOU	Active



CERDIP PACKAGE  
DIP-18C-C01

### PIN ASSIGNMENT



This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields. However, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high impedance circuit.

**MBM2148-55L / MBM2148-70 L****ABSOLUTE MAXIMUM RATINGS** (See Note)

Rating	Symbol	Value	Unit
Voltage On Any Pin with respect to $V_{SS}$	$V_{IN}, V_{OUT}, V_{CC}$	-3.5 to +7	V
Short Circuit Output Current	—	20	mA
Temperature Under Bias	$T_A$	-10 to +85	°C
Storage Temperature	$T_{stg}$	-65 to +150	°C
Power Dissipation	$P_D$	1.2	W

**NOTE:** Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to the conditions as detailed in the operations sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**CAPACITANCE**<sup>(1)</sup>

( $T_A = 25^\circ\text{C}$ ;  $f = 1\text{ MHz}$ )

Parameter	Symbol	Typ	Max	Unit
Address/Control Capacitance ( $V_{IN} = 0V$ )	$C_{IN}$	—	5	pF
Input/Output Capacitance ( $V_{OUT} = 0V$ )	$C_{I/O}$	—	7	pF

**NOTE:** 1) This parameter is sampled and not 100% tested.

**RECOMMENDED OPERATING CONDITIONS**

(Referenced to  $V_{SS}$ )

Parameter	Symbol	Min	Typ	Max	Unit	Ambient <sup>(1)</sup> Temperature
Supply Voltage	$V_{CC}$	4.5	5.0	5.5	V	0°C to +70°C
Input Low Voltage	$V_{IL}$	-3.0	—	0.8	V	
Input High Voltage	$V_{IH}$	2.1	—	6.0	V	

**NOTE:** 1. The operating ambient temperature range is guaranteed with transverse airflow exceeding 400 linear feet per minute.

**DC CHARACTERISTICS**

(Recommended operating conditions unless otherwise noted)

Parameter	Symbol	Min	Max	Unit
Input Leakage Current ( $V_{IN} = V_{SS}$ to $V_{CC}$ , $V_{CC} = \text{Max}$ )	$I_{LI}$	-10	10	$\mu\text{A}$
Output Leakage Current ( $\overline{CS} = V_{IH}$ , $V_{OUT} = V_{SS}$ to 4.5V, $V_{CC} = \text{Max}$ )	$I_{LO}$	-50	50	$\mu\text{A}$
Power Supply Current ( $V_{CC} = \text{Max}$ , $\overline{CS} = V_{IL}$ , $I_{OUT} = 0\text{mA}$ )	$I_{CC}$	—	125	mA
Output Low Voltage ( $I_{OL} = 8\text{mA}$ )	$V_{OL}$	—	0.4	V
Output High Voltage ( $I_{OH} = -4\text{mA}$ )	$V_{OH}$	2.4	—	V
Standby Current ( $V_{CC} = \text{Min to Max}$ , $\overline{CS} = V_{IH}$ , $I_{OUT} = 0\text{mA}$ )	$I_{SB}$	—	20	mA
Peak Power-On Current ( $V_{CC} = V_{SS}$ to $V_{CC}$ , Min $\overline{CS} = \text{Lower of } V_{CC} \text{ or } V_{IH} \text{ Min}$ )	$I_{PO}$	—	30	mA
Output Short Circuit Current ( $V_{OUT} = V_{SS}$ to $V_{CC}$ )	$I_{OS}$	-200	200	mA

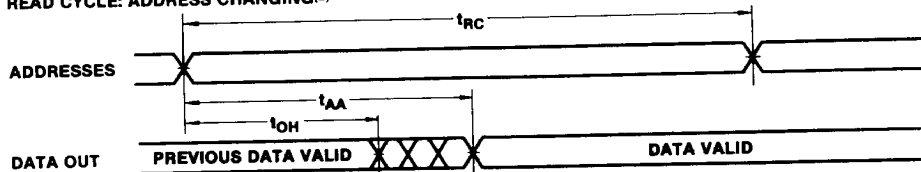
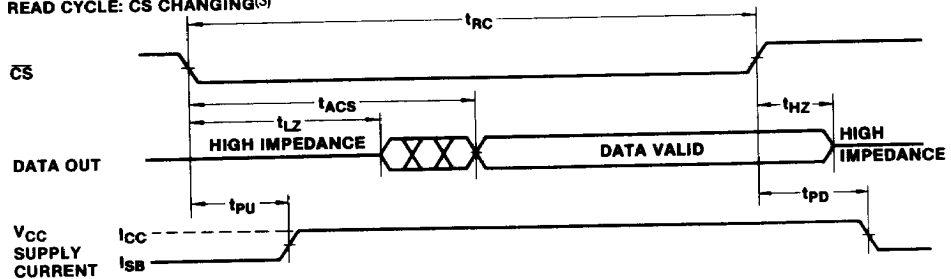
**AC CHARACTERISTICS**

(Recommended operating conditions unless otherwise noted.)

**READ CYCLE**

Parameter	NOTES	Symbol	MBM2148-55L			MBM2148-70L			Unit
			Min	Typ	Max	Min	Typ	Max	
Read Cycle Time		$t_{RC}$	55	—	—	70	—	—	ns
Address Access Time		$t_{AA}$	—	—	55	—	—	70	ns
Chip Select Access Time	[1]	$t_{ACS1}$	—	—	55	—	—	70	ns
Chip Select Access Time	[2]	$t_{ACS2}$	—	—	65	—	—	80	ns
Previous Read Data Valid After Change of Address		$t_{OH}$	5	—	—	5	—	—	ns
Chip Select to Power Up		$t_{PU}$	0	—	—	0	—	—	ns
Chip Select to Output Active	[3]	$t_{LZ}$	20	—	—	20	—	—	ns
Chip Select to Output Three-State	[3]	$t_{HZ}$	0	—	20	0	—	20	ns
Chip Select to Power Down		$t_{PD}$	—	—	30	—	—	30	ns

- NOTE:** 1. Chip deselected for greater than 55 ns prior to selection.  
 2. Chip deselected for a finite time that is less than 55 ns prior to selection. (If the deselect time is 0 ns, the chip is by definition selected and access occurs according to Read Cycle: Address Changing.)  
 3. Transition is measured  $\pm 500$  mV from high impedance voltage with LOAD B. This parameter is sampled and not 100% tested.

**READ CYCLE (1)****READ CYCLE: ADDRESS CHANGING(2)****READ CYCLE:  $\overline{CS}$  CHANGING(3)**

- NOTE:** 1.  $\overline{WE}$  is high for Read Cycle.  
 2. Device is continuously selected,  $\overline{CS} = V_{IL}$ .  
 3. Address valid prior to or coincident with  $\overline{CS}$  low transition.

# MBM2148-55L / MBM2148-70 L

## AC CHARACTERISTICS

(Recommended operating conditions unless otherwise noted.)

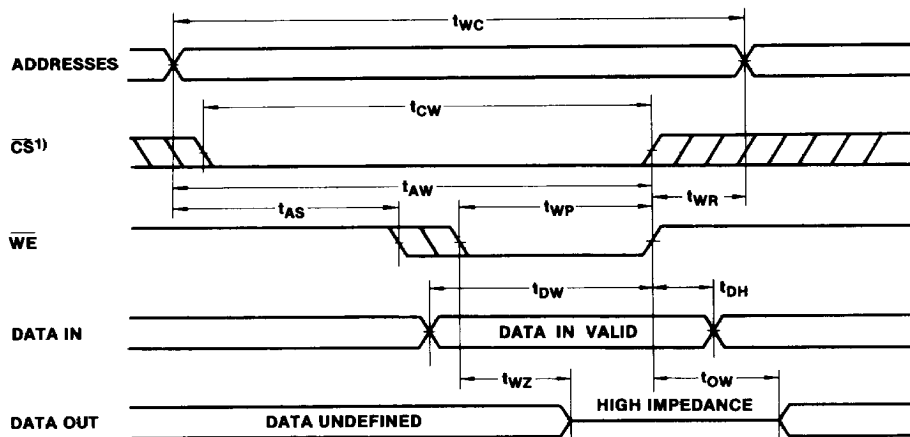
### WRITE CYCLE

Parameter	NOTES	Symbol	MBM2148-55L			MBM2148-70L			Unit
			Min	Typ	Max	Min	Typ	Max	
Write Cycle Time		$t_{WC}$	55	—	—	70	—	—	ns
Address Valid to End of Write		$t_{AW}$	50	—	—	65	—	—	ns
Chip Select to End of Write		$t_{CW}$	50	—	—	65	—	—	ns
Data Valid to End of Write		$t_{DW}$	20	—	—	25	—	—	ns
Data Hold Time		$t_{DH}$	0	—	—	0	—	—	ns
Write Pulse Width		$t_{WP}$	40	—	—	50	—	—	ns
Write Recovery Time		$t_{WR}$	5	—	—	5	—	—	ns
Address Setup Time		$t_{AS}$	0	—	—	0	—	—	ns
Output Active From End of Write	1	$t_{OW}$	0	—	—	0	—	—	ns
Write Enabled to Output Three-State	1	$t_{WZ}$	0	—	20	0	—	25	ns

NOTE: 1. Transition is measured  $\pm 500$  mV from high impedance voltage with LOAD B. This parameter is sampled and not 100% tested.

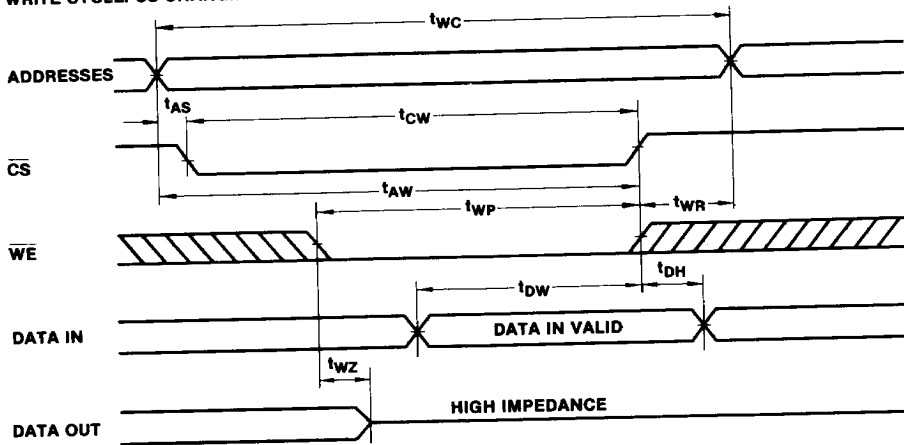
### WRITE CYCLE

#### WRITE CYCLE: $\overline{WE}$ CHANGING



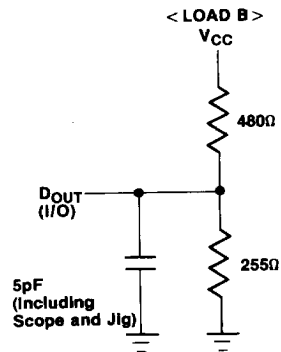
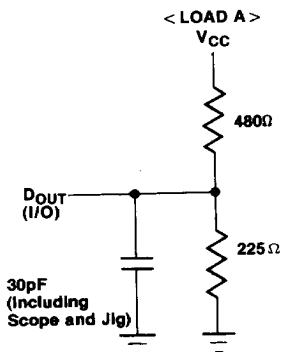
NOTE: 1. If  $\overline{CS}$  goes high simultaneously with  $\overline{WE}$  high, the output remains in a high impedance state.

## WRITE CYCLE

WRITE CYCLE:  $\overline{CS}$  CHANGING

## AC TEST CONDITIONS

Input Pulse Level: 0V to 3.0V  
 Input Pulse Rise and Fall Times: 5ns  
 Timing Measurement Reference Levels: Inputs: 1.5V  
 Outputs: 1.5V



## OVERVIEW

The MBM2148 family from Fujitsu are high performance parts. They are designed for high speed and low power system requirements.

The high speed is obtained by advanced NMOS processing. The low power system requirements are achieved by the use of the MBM2148's chip select (active low). The MBM2148 automatically enters standby (drawing only  $I_{SB}$ ) whenever the chip select is high. Upon activation of chip select ( $\overline{CS} = \text{LOW}$ ) the MBM2148 automatically powers up and draws  $I_{CC}$ .

This automatic power up/down is an extremely useful feature. PC board layout with proper  $V_{CC}$  decoupling will minimize power line glitches.

Input and data bus lines are an additional area of concern. Unless bus lines are properly designed and terminated, cross coupling, cross talk and reflections can occur. Of particular importance is the undershoot on address line. Once again, careful attention to good PC board layout and proper termination techniques will yield a well designed and reliable memory system.